

200V PNP LOW $V_{CE(sat)}$ TRANSISTOR IN SOT-89

Features

- BV_{CEO} > -200V
- BV_{ECO} > -2V
- Continuous current I_{C(cont)} = 2A
- V_{CE(sat} < -160mV @ -1A
- R_{CE(sat)}=130mΩ
- P_D = 2.4W
- 2 Amps continuous current
- Up to 5 Amps peak current
- · Very low saturation voltage
- Enhanced switching performance

Applications

DC-DC Convertors

Mechanical Data

- Case: SOT-89
- UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish
- Weight: 0.052 grams (approximate)

SOT-89

Top View

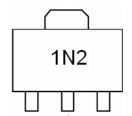
Device symbol

Pin Configuration

Ordering Information

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
ZXTP03200BZTA	1N2	7	12	1000

Marking Information



1N2 = Product type Marking Code

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Maximum Ratings @T_A = 25℃ unless otherwise specified

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	-220	V
Collector-Emitter Voltage	V_{CEO}	-200	V
Emitter-Base Voltage	V _{EBO}	-7	V
Continuous Collector Current (Note a)	Ic	-2	Α
Base Current	I _B	-1	Α
Peak Pulse Current	I _{CM}	-5	Α

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation at T _A = 25°C (Note a) Linear derating factor	PD	1.1 8.8	W mW /°C
Power Dissipation at $T_A = 25^{\circ}C$ (Note b) Linear derating factor	P _D	1.8 14.4	W mW /°C
Power Dissipation at $T_A = 25^{\circ}C$ (Note c) Linear derating factor	P_{D}	2.4 19.2	W mW /°C
Power Dissipation at T _A = 25°C (Note d) Linear derating factor	P_{D}	4.46 35.7	W mW /°C
Power Dissipation at T _A = 25°C (Note e) Linear derating factor	P_{D}	38.7 309.6	W mW /°C
Junction to Ambient (Note a)	$R_{ hetaJA}$	117	°C/W
Junction to Ambient (Note b)	$R_{ hetaJA}$	68	°C/W
Junction to Ambient (Note c)	$R_{ hetaJA}$	51	°C/W
Junction to Ambient (Note d)	$R_{ heta JA}$	28	°C/W
Junction to Lead (Note e)	$R_{ hetaJL}$	3.23	°C/W
Operating and Storage Temperature Range	T _{J,} T _{STG}	-55 to +150	°C

- a. For a device surface mounted on 15mm X 15mm X 1.6mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions
- b. Mounted on 25mm X 1.6mm FR4 PCB with high coverage of single sided 1 oz copper, in still air conditions. c. Mounted on 25mm X 1.6mm FR4 PCB with high coverage of single sided 2 oz copper, in still air conditions.
- d. As (c) above measured at t<5 seconds
- e. Junction to lead from collector Tab. Typical



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Thermal Characteristics and Derating information

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Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	V _{(BR)CBO}	-220	-245		V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage	$V_{(BR)CER}$	-220	-245		V	$I_C = -1\mu A, R_{BE} \le 1k\Omega$
Collector-Emitter Breakdown Voltage (Note f)	V _{(BR)CEO}	-220	-225		V	I _C = -10mA
Emitter-Base Breakdown Voltage	$V_{(BR)EBO}$	-7	-8.4		V	$I_E = -100 \mu A$
Collector-Base Cutoff Current	Ісво		<1	-50 -0.5	nΑ μΑ	V _{CB} = -200V V _{CB} = -200V, T _{amb} = 100℃
Emitter Cutoff Current	I _{EBO}		<1	-10	. nA	V _{EB} = -6V
Static Forward Current Transfer Ratio (Note f)	h _{FE}	100 100 20	195 179 50 5	300		I _C = -10mA, V _{CE} = -5V I _C = -1A, V _{CE} = -5V I _C = -2A, V _{CE} = -5V I _C = -5A, V _{CE} = -5V
Collector-Emitter Saturation Voltage (Note f)	V _{CE(SAT)}		-37 -120 -130 -160	-50 -155 -160 -260	mV mV mV	$I_C = -100$ mA, $I_B = -10$ mA $I_C = -500$ mA, $I_B = -25$ mA $I_C = -1$ A, $I_B = -100$ mA $I_C = -2$ A, $I_B = -400$ mA
Base-Emitter Saturation Voltage (Note f)	V _{BE(sat)}		-940	-1100	mV	$I_C = -2A$, $I_B = -400$ mV
Base-Emitter Turn-On Voltage (Note f)	V _{BE(ON)}		-840	-1000	mV	$I_C = -2A$, $V_{CE} = -5V$
Output Capacitance (Note f)	C_{obo}		31		pF	$V_{CB} = -10V. f = 1MHz$
Transition Frequency	f _T		105		MHz	$V_{CE} = -10V, I_{C} = -100mA$ f = 50MHz
Delay Time	t _d		21	_	ns	
Rise Time	t _r		18		ns	$V_{CC} = -50V, I_{C} = -1A$
Storage Time	Ts		680		ns	$I_{B1} = -I_{B2} = -100 \text{mA}$
Fall Time	T _f		75		ns	

Notes: f. Measured under pulsed conditions. Pulse width = 300 μ s. Duty cycle \leq 2%



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Typical Characteristics		



200V PNP LOW $V_{\text{CE(sat)}}$ TRANSISTOR IN SOT-89

ckage Outline Dimensions
ggested Pad Layout



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